

**IN THE SPECIFICATION:**

Please replace paragraph [0044] with the following.

[0044] It should be noted that the layer of resilient conductive material 130 may be sandwiched between a lower dielectric layer of substrate 120 and an upper dielectric layer thereof which overlies layer of resilient conductive material 130, upper dielectric layer defining upper surface 124. Referring to FIGS. 4 and 5 of the drawings, an exemplary overlying dielectric or insulative layer 121 having apertures 123 therein substantially aligned with apertures 136 may be disposed over the layer of resilient conductive material 130 after formation of the conductive traces 132 and spring-biased electrical contacts 160. The apertures in overlying dielectric layer 121 may be sized and configured to receive portions of conductive balls 41 of a BGA package (see FIG. 5 and description below) therein, and overlying dielectric layer may be of sufficient thickness to assist with alignment of conductive balls 41 with spring-biased electrical contacts 160. If desired, apertures 123 may be of frustoconical shape as shown ~~at broken lines~~ by aperture 123' with a wider upper portion to assist in the initial alignment of conductive balls 41.